

**Description:**

The SLR1117 is a low dropout, three terminals regulator designed to provide output current up to 800mA. The device is available in an adjustable version and fixed output voltage of 1.8V, 2.5V and 3.3V. Dropout voltage of maximum of 1.4V is guaranteed at 800mA output current. The quality of low dropout voltage and fast transient response make this device ideal for low voltage microprocessor applications.

The SLR1117 requires output capacitance of a minimum of 10µF for stability. Built-in output current limiting and thermal limiting provide maximal protection to the SLR1117 against fault conditions.

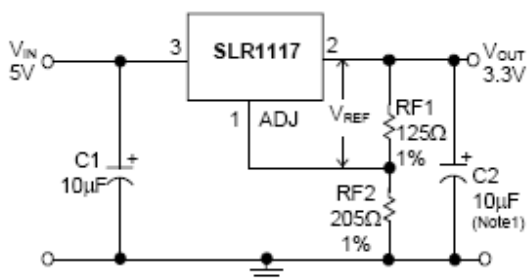
**Features:**

- Dropout Voltage 1.2V at 800mA Output Current.
- Fast Transient Response.
- Line Regulation, typical at 0.015%.
- Load Regulation, typical at 0.1%.
- Current Limiting and Thermal Protection.
- Adjustable Output Voltage or Fixed 1.8V, 2.5V and 3.3V.
- Standard 3-Pin Power Packages.

**Applications:**

- Active SCSI Terminators.
- Post Regulators for Switching Supplies.
- Battery Chargers.
- PC Add-On Card.

**Typical application circuit:**



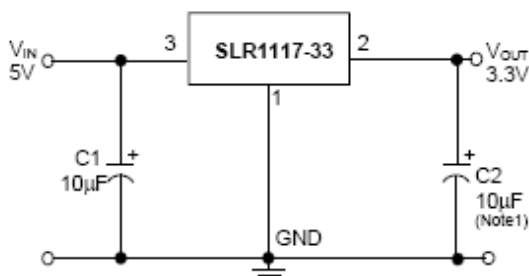
**Adjustable Voltage Regulator**

$$V_{REF} = V_{OUT} - V_{ADJ} = 1.25V \text{ (typ.)}$$

$$V_{OUT} = V_{REF} \times (1 + R_{F2}/R_{F1}) + I_{ADJ} \times R_{F2}$$

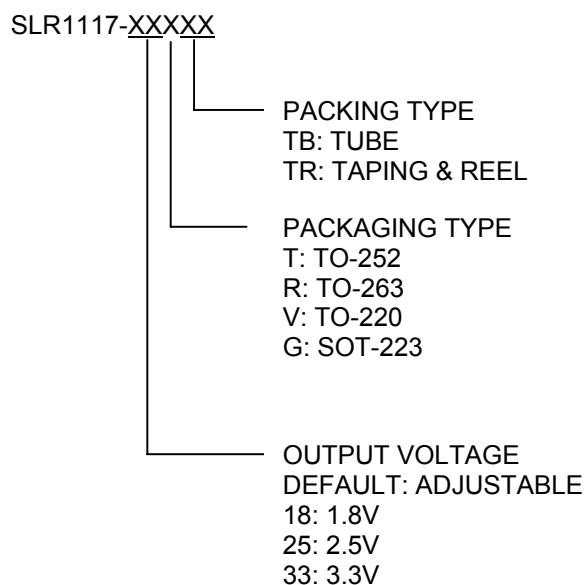
$$I_{ADJ} = 55\mu A \text{ (typ.)}$$

- (1) C1 needed if device is far away from filter capacitors.
- (2) C2 required for stability.



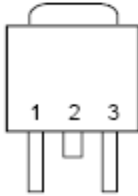
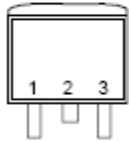
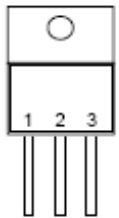
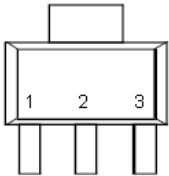
**Fixed Voltage Regulator**

Ordering Information:



Example: SLR1117-25TTR  
 → 2.5V version in TO-252 Green  
 Package & Taping & Reel Packing Type

Example: SLR1117-25GTR  
 → 2.5V version in SOT-223 Lead Free  
 Package & Taping & Reel Packing Type

PIN CONFIGURATION	
TO-252 TOP VIEW  1: ADJ (GND) 2: VOUT (TAB) 3: VIN	
TO-263 TOP VIEW  1: ADJ (GND) 2: VOUT (TAB) 3: VIN	
TO-220 FRONT VIEW  1: ADJ (GND) 2: VOUT (TAB) 3: VIN	
SOT-223 FRONT VIEW  1: ADJ (GND) 2: VOUT (TAB) 3: VIN	

Marking Diagram:

Part No.	Marking
SLR1117-33GTR	AK33G



**Technical Data**  
**Data Sheet N1575, Rev. -**
**800mA Low Dropout Positive Regulator**
**Electrical Characteristics**
 $(V_{IN}=5V, T_J=25^{\circ}C, I_O=10mA, \text{ unless otherwise specified})$  (Note2)

PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Reference Voltage	SLR1117 (ADJ), $T_J=25^{\circ}C$	1.238	1.25	1.262	V
	$0^{\circ}C \leq T_J \leq 125^{\circ}C$	1.225	1.25	1.275	
Output Voltage	SLR1117-18, $V_{IN}=3.3V$	1.78	1.8	1.82	V
	SLR1117-25, $V_{IN}=5V$	2.47	2.5	2.53	
	SLR1117-33, $V_{IN}=5V$	3.26	3.30	3.33	
Line Regulation	$2.65 \leq V_{IN} \leq 7V, V_{OUT}=1.25V$ $T_J=25^{\circ}C$		0.015	0.2	%
	$0^{\circ}C \leq T_J \leq 125^{\circ}C$		0.035	0.2	
Load Regulation	$T_J=25^{\circ}C$ $10mA \leq I_O \leq 800mA$		0.1	0.3	%
	$0^{\circ}C \leq T_J \leq 125^{\circ}C$		0.2	0.4	
Dropout Voltage	$\Delta V_{OUT}, \Delta V_{REF}=1\%$ $10mA \leq I_O \leq 800mA$		1.2	1.4	V
Current Limit		0.85			A
Adjusted Pin Current ( $I_{ADJ}$ )	$2.65 \leq V_{IN} \leq 7V$ $10mA \leq I_O \leq 800mA$		55	120	$\mu A$
Adjusted Pin Current Change ( $\Delta I_{ADJ}$ )	$2.65 \leq V_{IN} \leq 7V$ $10mA \leq I_O \leq 800mA$		0.2	5	$\mu A$
Temperature Stability	$I_O=0.5A$		0.5		%
Minimum Load Current			5	10	mA
GND Current	$2.65 \leq V_{IN} \leq 7V$		10	14	mA
RMS Output Noise (% of $V_{OUT}$ )	$10Hz \leq f \leq 10KHz$		0.003		%
Ripple Rejection Ratio	120Hz input ripple $C_{OUT}=25\mu F$	60	72		dB

**Note 1:** To avoid output oscillation, aluminum electrolytic output capacitor is recommended and ceramic capacitor is not suggested.

**Note 2:** Specifications are production tested at  $T_A=25^{\circ}C$ . Specifications over the  $-40^{\circ}C$  to  $85^{\circ}C$  operating temperature range are assured by design, characterization and correlation with Statistical Quality Controls (SQC).

Technical Data  
Data Sheet N1575, Rev. -

800mA Low Dropout Positive Regulator

Typical Performance Characteristics

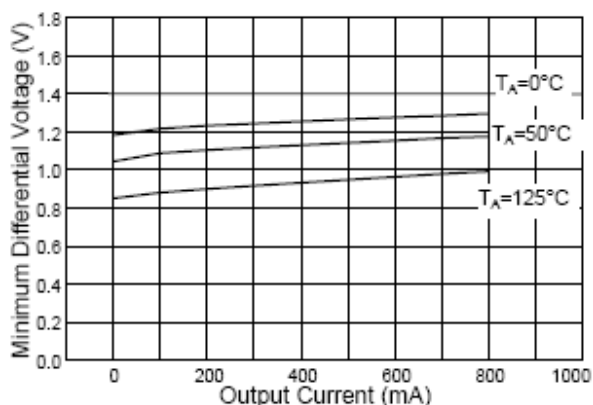


Fig. 1 AIC1117 (ADJ) Dropout Voltage

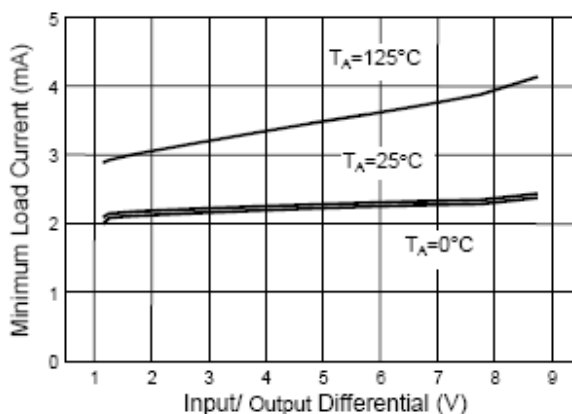


Fig. 2 Minimum Load Current (Adjustable Version)

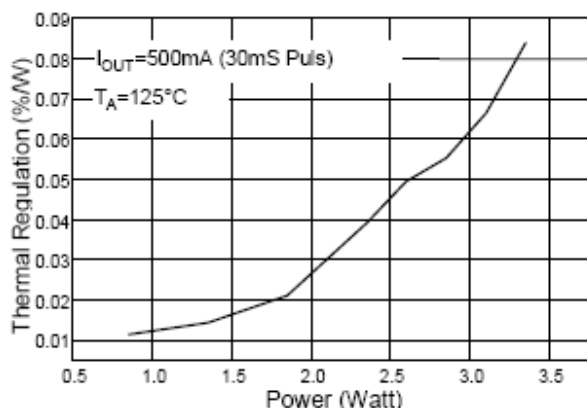


Fig. 3 AIC1117 (ADJ) Power vs. Thermal Regulation

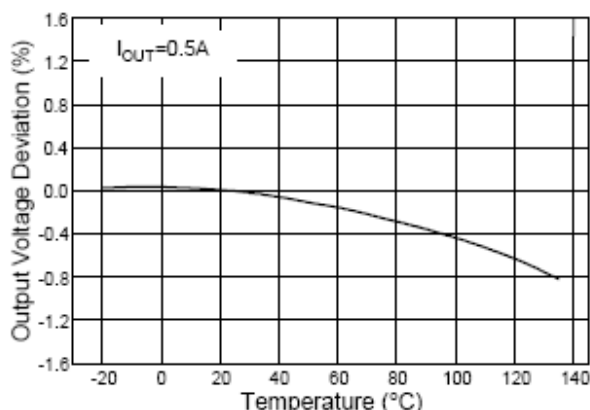


Fig. 4 AIC1117 (ADJ) Temperature Stability

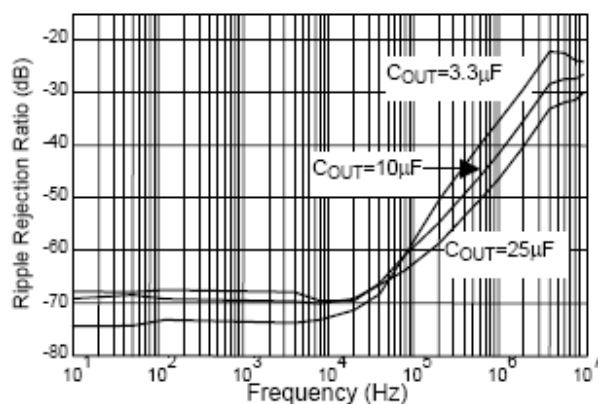


Fig. 5 AIC1117 (ADJ) Ripple Rejection Ratio (dB)

Typical Performance Characteristics (Continued)

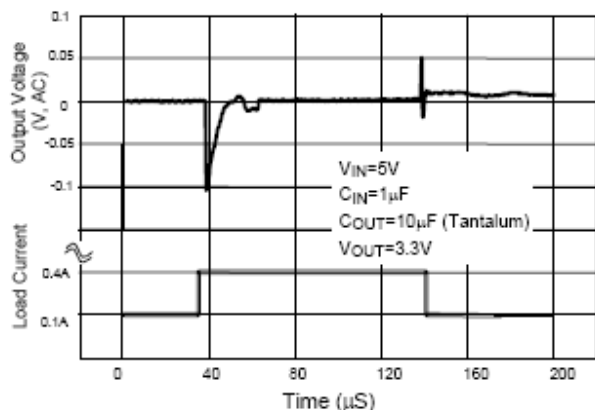


Fig. 6 Load Transient Response

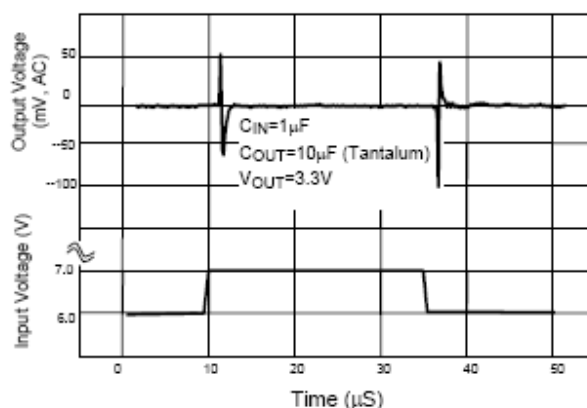


Fig. 7 Line Transient Response

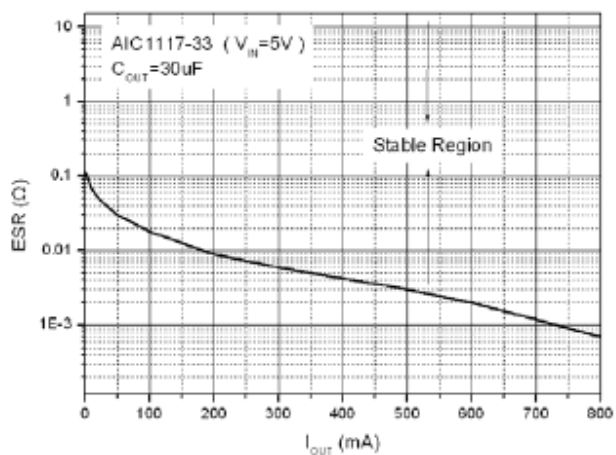


Fig. 8 Region of Stable  $C_{OUT}$  ESR vs. Load Current

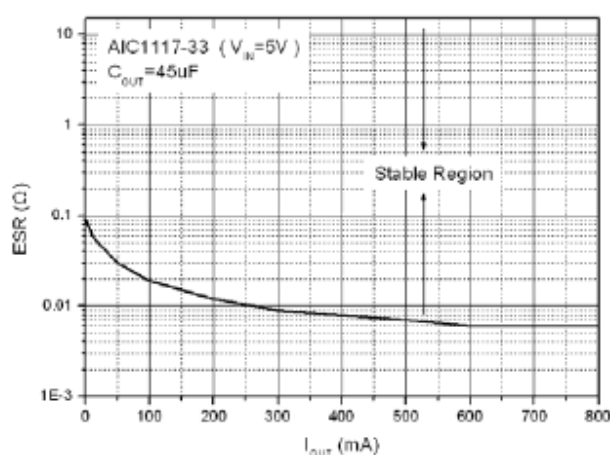
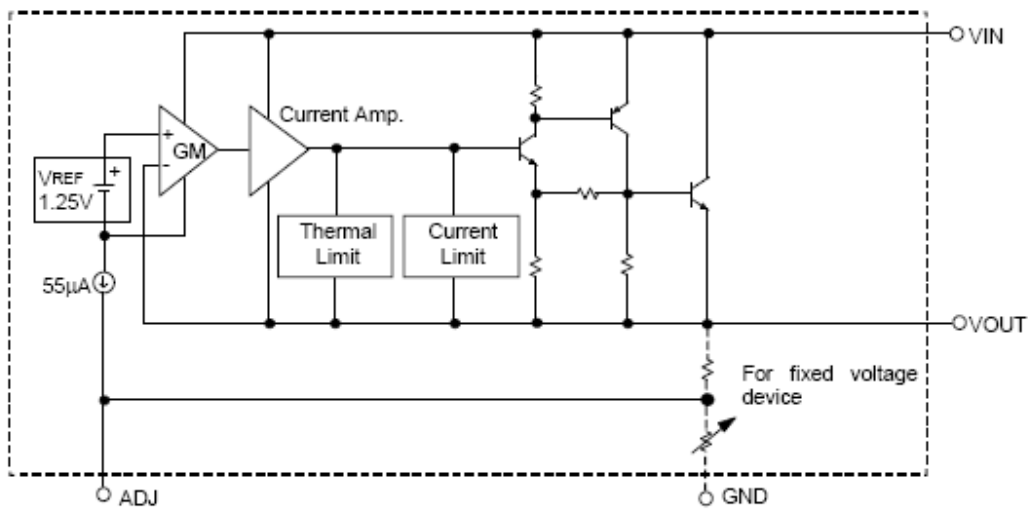


Fig. 9 Region of Stable  $C_{OUT}$  ESR vs. Load Current

**Block Diagram**



**Pin Descriptions**

- ADJ PIN - Providing  $V_{REF} = 1.25V$  (typ.) for adjustable  $V_{OUT}$ .  $V_{REF} = V_{OUT} - V_{ADJ}$  and  $I_{ADJ} = 55\mu A$  (typ.)  
(GND PIN- Power ground.)
- VOUT PIN - Adjustable output voltage.
- VIN PIN - Power Input.

### Application Information

#### INPUT-OUTPUT CAPACITORS

Linear regulators require input and output capacitors to maintain stability. Input capacitor at 10µF with a 10µF aluminum electrolytic output capacitor is recommended. To avoid oscillation, it is recommended to follow Fig. 8, 9 to choose proper capacitor specifications.

#### POWER DISSIPATION

The SLR1117 obtains thermal-limiting circuitry, which is designed to protect the device against overload condition. For continuous load condition, maximum rating of junction temperature must not be exceeded. It is important to pay more attention in thermal resistance. It includes junction to case, junction to ambient. The maximum power dissipation of SLR1117 depends on the thermal resistance of its case and circuit board, the temperature difference between the die junction and ambient air, and the rate of airflow. The rate of temperature rise is greatly affected by the mounting pad configuration on the PCB, the board material, and the ambient temperature. When the IC mounting with good thermal conductivity is used, the junction temperature will be low even when large power dissipation applies.

The power dissipation across the device is  $P = I_{OUT} (V_{IN} - V_{OUT})$ .

The maximum power dissipation is:

$$P_{MAX} = \frac{(T_{J-max} - T_A)}{R_{\theta JA}}$$

Where  $T_{J-max}$  is the maximum allowable junction temperature (125°C), and  $T_A$  is the ambient temperature suitable in application.

As a general rule, the lower temperature is, the better reliability of the device is. So the PCB mounting pad should provide maximum thermal conductivity to maintain low device temperature.

### Application Examples

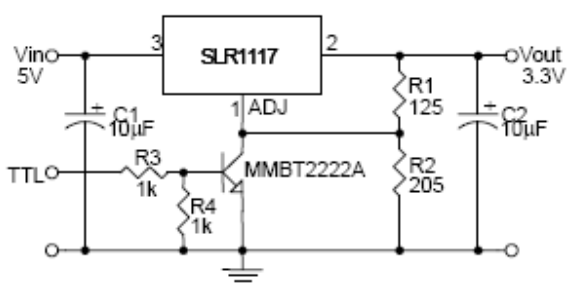
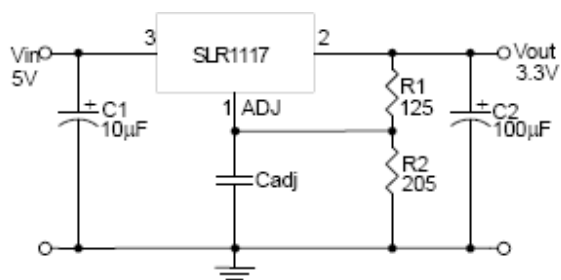


Fig. 10  $V_{OUT}=3.3V$  with Shutdown



\* Cadj can improve ripple rejection

Fig. 11 Improving Ripple Rejection

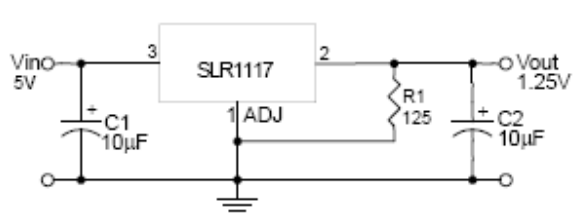


Fig. 12  $V_{OUT}=1.25V$  Application Circuit

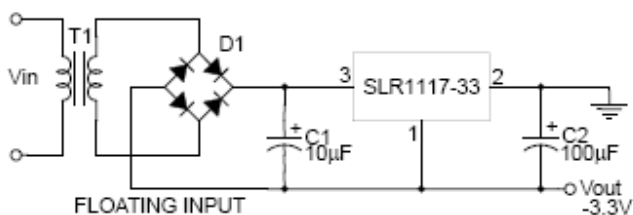
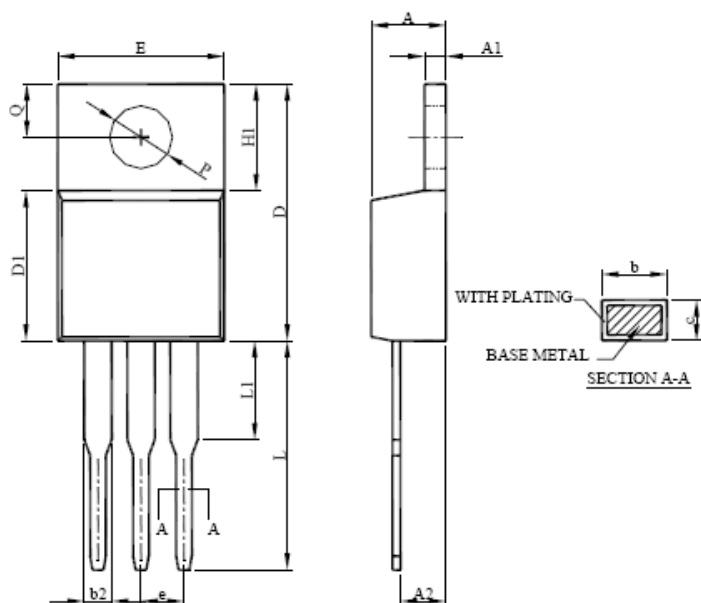


Fig. 13 Low Dropout Negative Supply



Physical Dimensions

TO-220 (unit: mm)

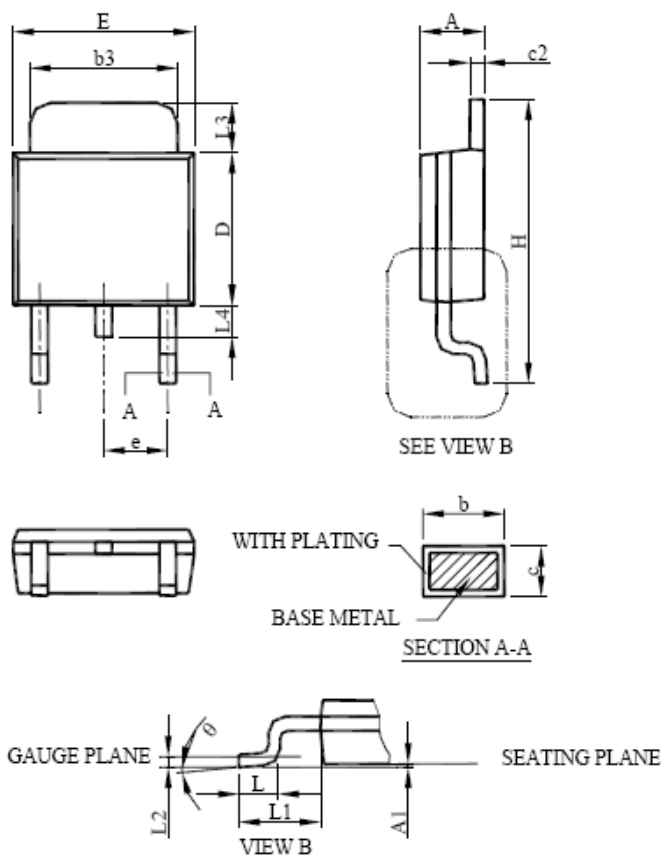


SYMBOL	TO-220	
	MILLIMETERS	
	MIN.	MAX.
A	3.56	4.82
A1	0.51	1.39
A2	2.04	2.92
b	0.38	1.01
b2	1.15	1.77
c	0.35	0.61
D	14.23	16.51
D1	8.38	9.02
E	9.66	10.66
e	2.54 BSC	
H1	5.85	6.85
L	12.70	14.73
L1	--	6.35
P	3.54	4.08
Q	2.54	3.42

Note:

1. Refer to JEDEC TO-220AB.
2. Dimension "E" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
3. Dimension "D1" does not include inter-lead flash or protrusions.
4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

TO-252 (unit: mm)

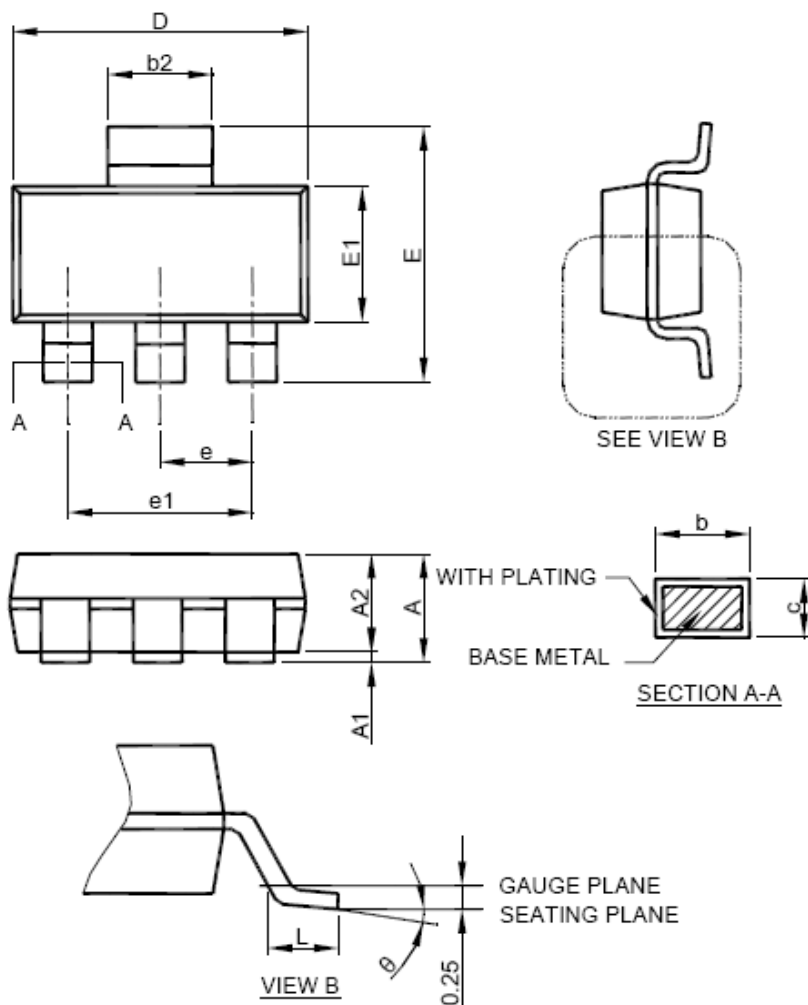


SYMBOL	TO-252-3L	
	MILLIMETERS	
	MIN.	MAX.
A	2.19	2.38
A1	0.00	0.13
b	0.64	0.89
b3	4.95	5.46
c	0.46	0.61
c2	0.46	0.89
D	5.33	6.22
E	6.35	6.73
e	2.28 BSC	
H	9.40	10.41
L	1.40	1.78
L1	2.67 REF	
L2	0.51 BSC	
L3	0.89	2.03
L4	--	1.02
θ	0°	8°

Note:

1. Refer to JEDEC TO-252AA and AB.
2. Dimension "E" do not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
3. Dimension "D" does not include inter-lead flash or protrusions.
4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

SOT-223(unit: mm)



SYMBOL	SOT-223	
	MILLIMETERS	
	MIN.	MAX.
A		1.80
A1	0.02	0.10
A2	1.55	1.65
b	0.66	0.84
b2	2.90	3.10
c	0.23	0.33
D	6.30	6.70
E	6.70	7.30
E1	3.30	3.70
e	2.30 BSC	
e1	4.60 BSC	
L	0.90	
θ	0°	8°

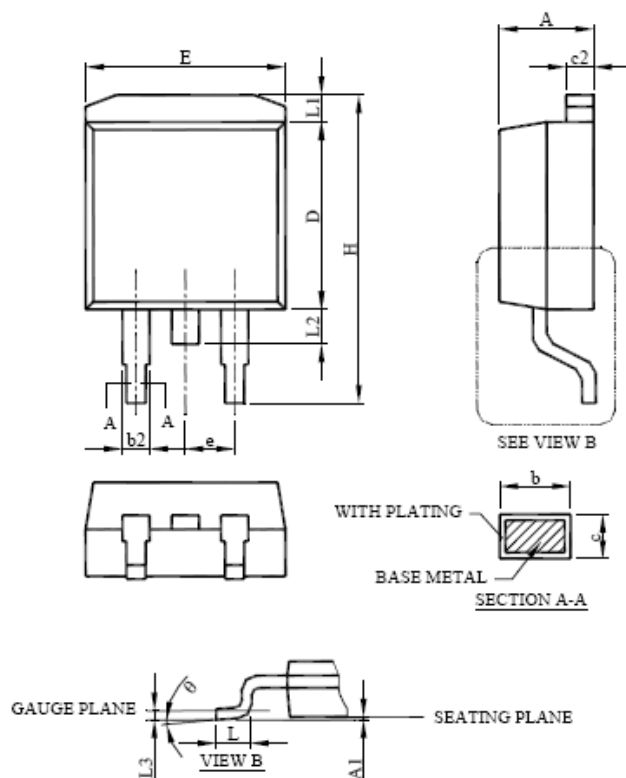
Note: 1. Refer to JEDEC TO-261AA.

2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side .

3. Dimension "E1" does not include inter-lead flash or protrusions.

4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

TO-263 (unit: mm)



SYMBOL	TO-263-3L	
	MILLIMETERS	
	MIN.	MAX.
A	4.06	4.83
A1	0.00	0.25
b	0.51	0.99
b2	1.14	1.78
c	0.38	0.74
c2	1.14	1.65
D	8.38	9.65
E	9.65	10.67
e	2.54 BSC	
H	14.61	15.88
L	1.78	2.79
L1	--	1.68
L2	--	1.78
L3	0.25 BSC	
θ	0°	8°

Note:

1. Refer to JEDEC TO-263AB.
2. Dimension "E" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
3. Dimension "D" does not include inter-lead flash or protrusions.
4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.



SLR1117

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Data Sheet N1575, Rev. -

800mA Low Dropout Positive Regulator

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